


**Features**

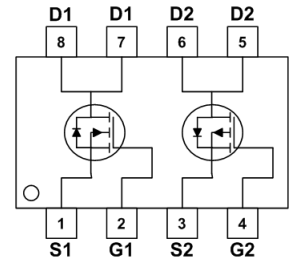
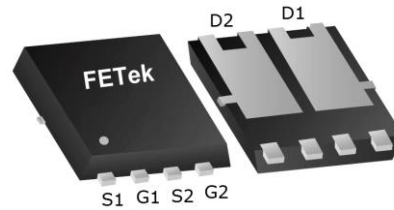
- ★ Advanced Trench MOS Technology
- ★ 100% EAS Guaranteed
- ★ Green Device Available

**Product Summary**

BVDSS	RDSON(Typ.)	ID
60V	38mΩ	5A
-60V	75mΩ	-3.8A

**Applications**

- ★ Synchronous Rectification.
- ★ Motor Control.
- ★ High Current, High Speed Switching.
- ★ Portable equipment application.

**PRPAK3X3 Pin Configuration**

**Absolute Maximum Ratings**

Symbol	Parameter	Rating		Units
		N-Channel	P-Channel	
$V_{DS}$	Drain-Source Voltage	60	-60	V
$V_{GS}$	Gate-Source Voltage	$\pm 20$	$\pm 20$	V
$I_D@T_A=25^\circ C$	Continuous Drain Current, $V_{GS} @ 10V^1$	5	-3.8	A
$I_D@T_A=70^\circ C$	Continuous Drain Current, $V_{GS} @ 10V^1$	4	-3.2	A
$I_{DM}$	Pulsed Drain Current <sup>2</sup>	20	-14	A
EAS	Single Pulse Avalanche Energy <sup>3</sup>	22	28.8	mJ
$I_{AS}$	Avalanche Current	21	-24	A
$P_D@T_A=25^\circ C$	Total Power Dissipation <sup>4</sup>	2	2	W
$T_{STG}$	Storage Temperature Range	-55 to 150	-55 to 150	$^\circ C$
$T_J$	Operating Junction Temperature Range	-55 to 150	-55 to 150	$^\circ C$

**Thermal Data**

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction-Ambient <sup>1</sup>	---	85	$^\circ C/W$
	Thermal Resistance Junction-Ambient <sup>1</sup> ( $t \leq 10sec$ )	---	62.5	$^\circ C/W$

**N-Channel Electrical Characteristics ( $T_J=25^\circ\text{C}$ , unless otherwise noted)**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=250\mu A$	60	---	---	V
$R_{DS(ON)}$	Static Drain-Source On-Resistance <sup>2</sup>	$V_{GS}=10V, I_D=5A$	---	38	50	m $\Omega$
		$V_{GS}=4.5V, I_D=4A$	---	45	70	
$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS}=V_{DS}, I_D=250\mu A$	1.0	---	2.5	V
$I_{DSS}$	Drain-Source Leakage Current	$V_{DS}=48V, V_{GS}=0V, T_J=25^\circ\text{C}$	---	---	1	$\mu A$
		$V_{DS}=48V, V_{GS}=0V, T_J=55^\circ\text{C}$	---	---	5	
$I_{GSS}$	Gate-Source Leakage Current	$V_{GS}=\pm 20V, V_{DS}=0V$	---	---	$\pm 100$	nA
$g_{fs}$	Forward Transconductance	$V_{DS}=5V, I_D=4A$	---	28	---	S
$R_g$	Gate Resistance	$V_{DS}=0V, V_{GS}=0V, f=1\text{MHz}$	---	2.8	---	$\Omega$
$Q_g$	Total Gate Charge (4.5V)	$V_{DS}=48V, V_{GS}=4.5V, I_D=4A$	---	19	---	nC
$Q_{gs}$	Gate-Source Charge		---	2.6	---	
$Q_{gd}$	Gate-Drain Charge		---	4.1	---	
$T_{d(on)}$	Turn-On Delay Time	$V_{DD}=30V, V_{GS}=10V, R_G=3.3\Omega, I_D=4A$	---	3	---	ns
$T_r$	Rise Time		---	34	---	
$T_{d(off)}$	Turn-Off Delay Time		---	23	---	
$T_f$	Fall Time		---	6	---	
$C_{iss}$	Input Capacitance	$V_{DS}=15V, V_{GS}=0V, f=1\text{MHz}$	---	1027	---	$\mu F$
$C_{oss}$	Output Capacitance		---	65	---	
$C_{rss}$	Reverse Transfer Capacitance		---	46	---	

**Diode Characteristics**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$I_S$	Continuous Source Current <sup>1,5</sup>	$V_G=V_D=0V$ , Force Current	---	---	2.5	A
$V_{SD}$	Diode Forward Voltage <sup>2</sup>	$V_{GS}=0V, I_S=1A, T_J=25^\circ\text{C}$	---	---	1.2	V

Note :

- 1.The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width  $\leq 300\mu s$  , duty cycle  $\leq 2\%$
- 3.The EAS data shows Max. rating . The test condition is  $V_{DD}=25V, V_{GS}=10V, L=0.1mH, I_{AS}=21A$
- 4.The power dissipation is limited by  $150^\circ\text{C}$  junction temperature
- 5.The data is theoretically the same as  $I_D$  and  $I_{DM}$  , in real applications , should be limited by total power dissipation.

**P-Channel Electrical Characteristics ( $T_J=25^\circ\text{C}$ , unless otherwise noted)**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=-250\mu A$	-60	---	---	V
$R_{DS(ON)}$	Static Drain-Source On-Resistance <sup>2</sup>	$V_{GS}=-10V, I_D=-3A$	---	75	100	m $\Omega$
		$V_{GS}=-4.5V, I_D=-3A$	---	90	120	
$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS}=V_{DS}, I_D=-250\mu A$	-1.0	---	-2.5	V
$I_{DSS}$	Drain-Source Leakage Current	$V_{DS}=-48V, V_{GS}=0V, T_J=25^\circ\text{C}$	---	---	1	$\mu A$
		$V_{DS}=-48V, V_{GS}=0V, T_J=55^\circ\text{C}$	---	---	5	
$I_{GSS}$	Gate-Source Leakage Current	$V_{GS}=\pm 20V, V_{DS}=0V$	---	---	$\pm 100$	nA
$g_{fs}$	Forward Transconductance	$V_{DS}=-5V, I_D=-3A$	---	15	---	S
$R_g$	Gate Resistance	$V_{DS}=0V, V_{GS}=0V, f=1\text{MHz}$	---	13.5	---	$\Omega$
$Q_g$	Total Gate Charge (-4.5V)	$V_{DS}=-48V, V_{GS}=-4.5V, I_D=-3A$	---	9.86	---	nC
$Q_{gs}$	Gate-Source Charge		---	3.08	---	
$Q_{gd}$	Gate-Drain Charge		---	2.95	---	
$T_{d(on)}$	Turn-On Delay Time	$V_{DD}=-15V, V_{GS}=-10V, R_G=3.3\Omega, I_D=-1A$	---	28.8	---	ns
$T_r$	Rise Time		---	19.8	---	
$T_{d(off)}$	Turn-Off Delay Time		---	60.8	---	
$T_f$	Fall Time		---	7.2	---	
$C_{iss}$	Input Capacitance	$V_{DS}=-15V, V_{GS}=0V, f=1\text{MHz}$	---	1447	---	$\mu F$
$C_{oss}$	Output Capacitance		---	97.3	---	
$C_{rss}$	Reverse Transfer Capacitance		---	70	---	

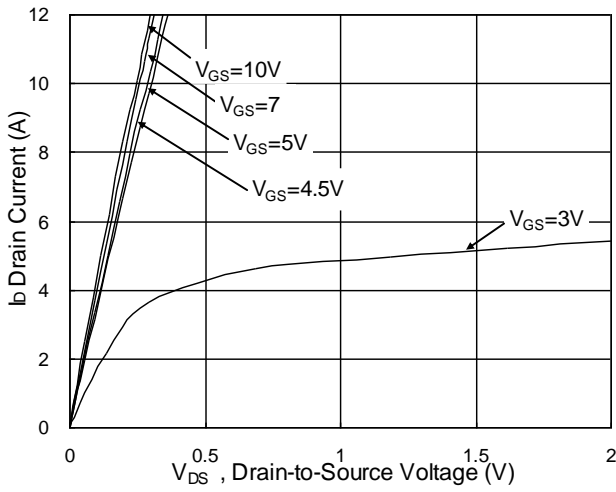
**Diode Characteristics**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$I_S$	Continuous Source Current <sup>1,5</sup>	$V_G=V_D=0V$ , Force Current	---	---	-2.5	A
$V_{SD}$	Diode Forward Voltage <sup>2</sup>	$V_{GS}=0V, I_S=-1A, T_J=25^\circ\text{C}$	---	---	-1.2	V

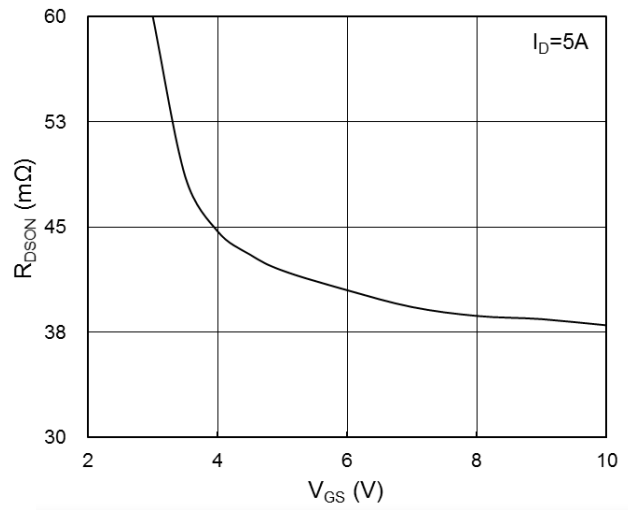
Note :

- 1.The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 20Z copper.
- 2.The data tested by pulsed , pulse width  $\leq 300\mu s$  , duty cycle  $\leq 2\%$
- 3.The EAS data shows Max. rating . The test condition is  $V_{DD}=-25V, V_{GS}=-10V, L=0.1mH, I_{AS}=-24A$
- 4.The power dissipation is limited by 150 $^\circ\text{C}$  junction temperature
- 5.The data is theoretically the same as  $I_D$  and  $I_{DM}$  , in real applications , should be limited by total power dissipation.

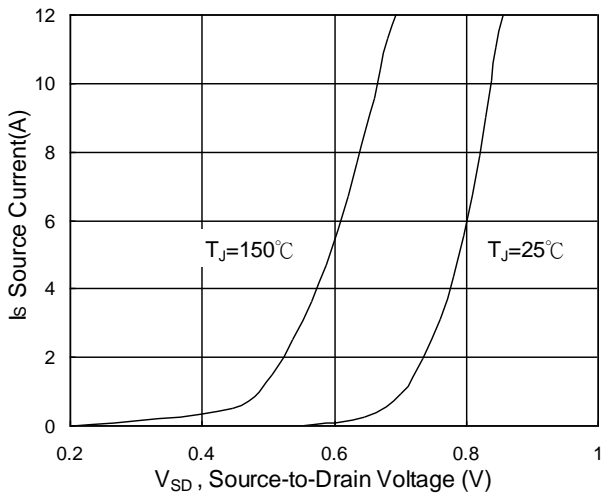
**N-Channel Typical Characteristics**



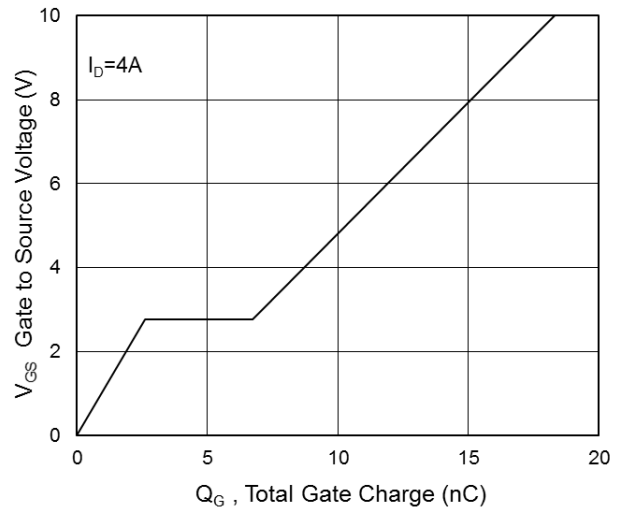
**Fig.1 Typical Output Characteristics**



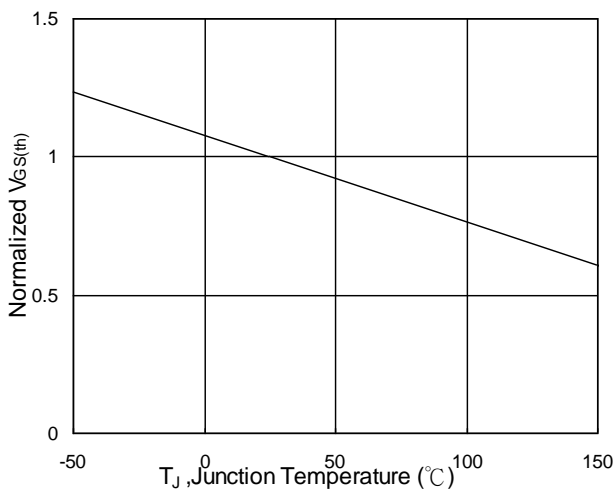
**Fig.2 On-Resistance vs G-S Voltage**



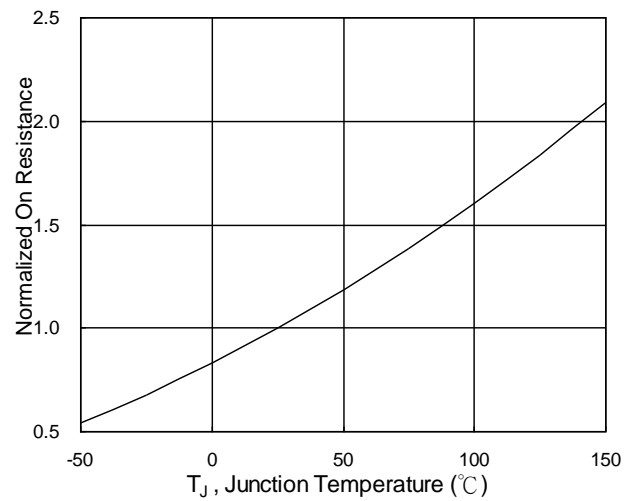
**Fig.3 Source Drain Forward Characteristics**



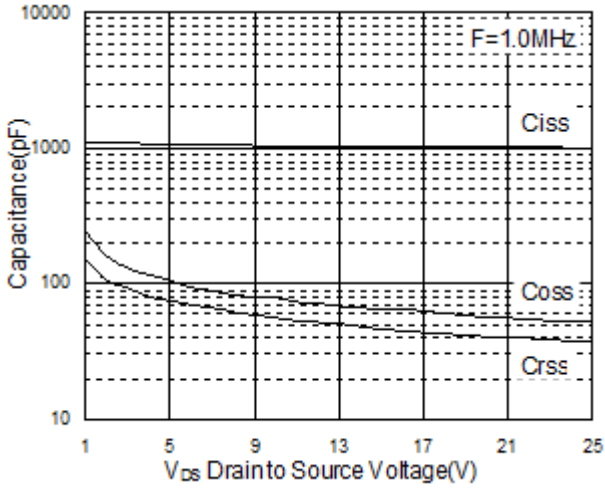
**Fig.4 Gate-Charge Characteristics**



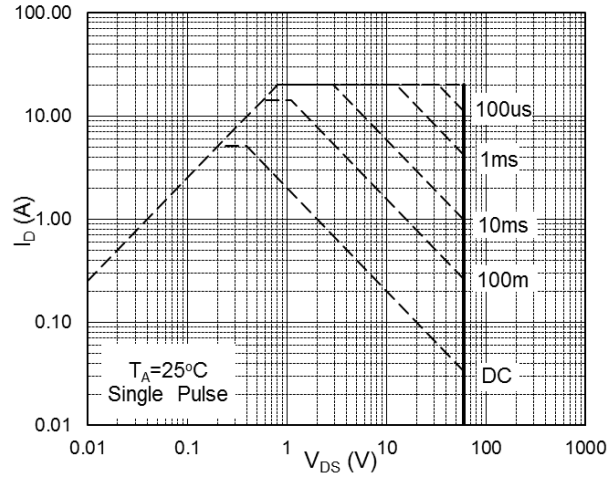
**Fig.5 Normalized  $V_{GS(th)}$  vs  $T_J$**



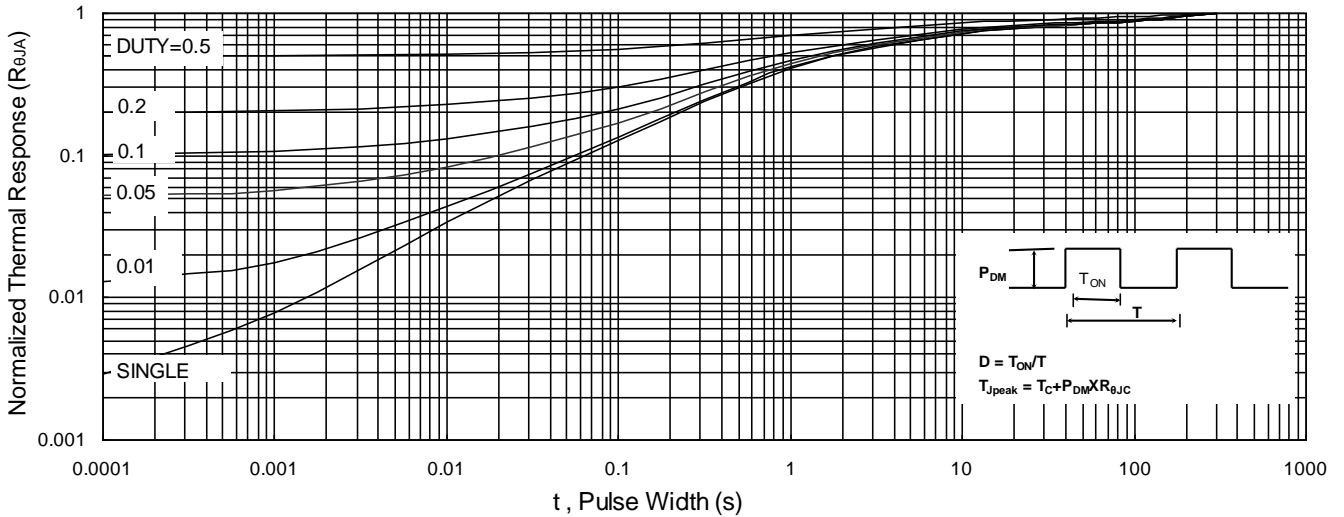
**Fig.6 Normalized  $R_{DS(on)}$  vs  $T_J$**



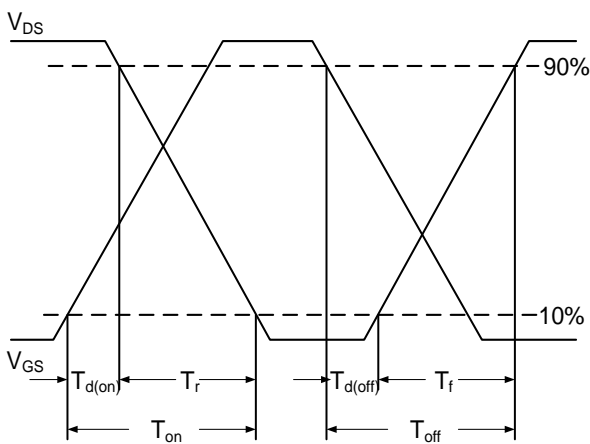
**Fig.7 Capacitance**



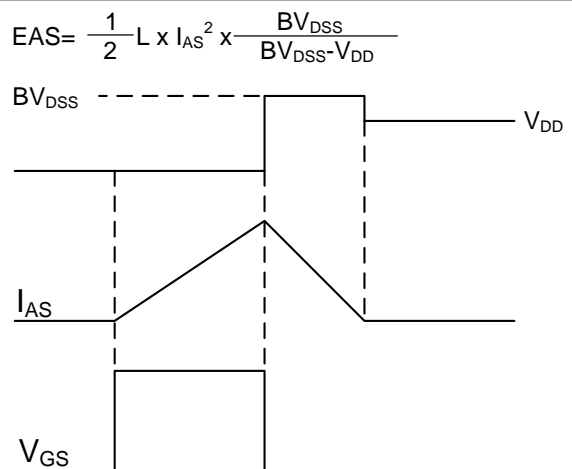
**Fig.8 Safe Operating Area**



**Fig.9 Normalized Maximum Transient Thermal Impedance**

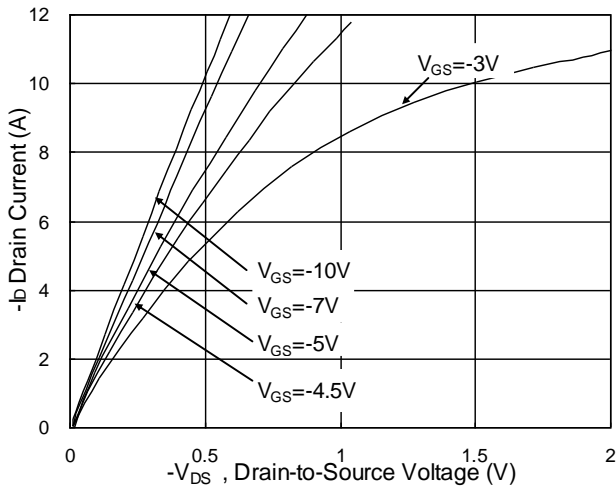


**Fig.10 Switching Time Waveform**

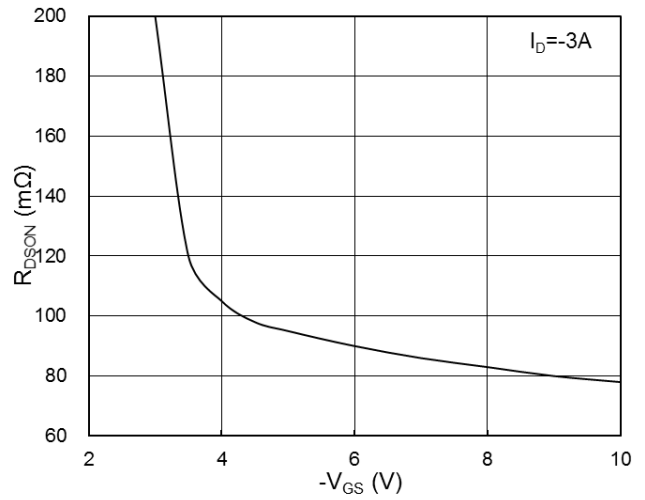


**Fig.11 Unclamped Inductive Waveform**

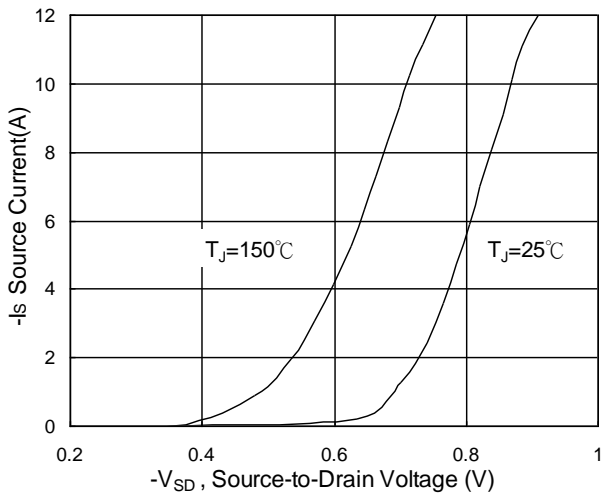
**P-Channel Typical Characteristics**



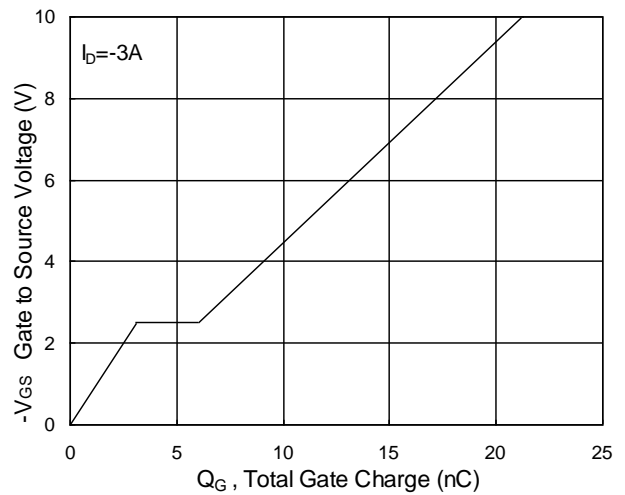
**Fig.1 Typical Output Characteristics**



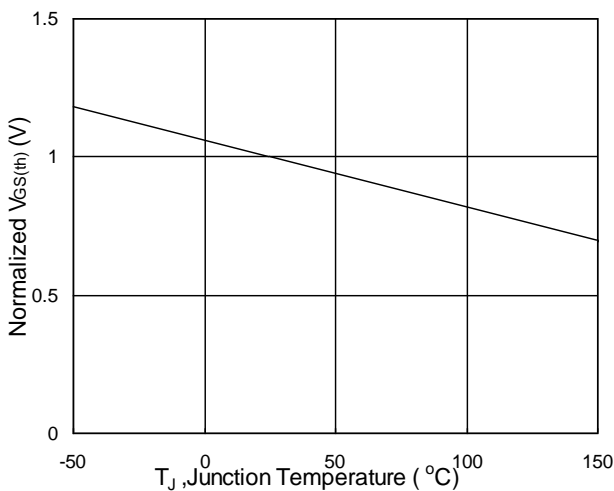
**Fig.2 On-Resistance vs G-S Voltage**



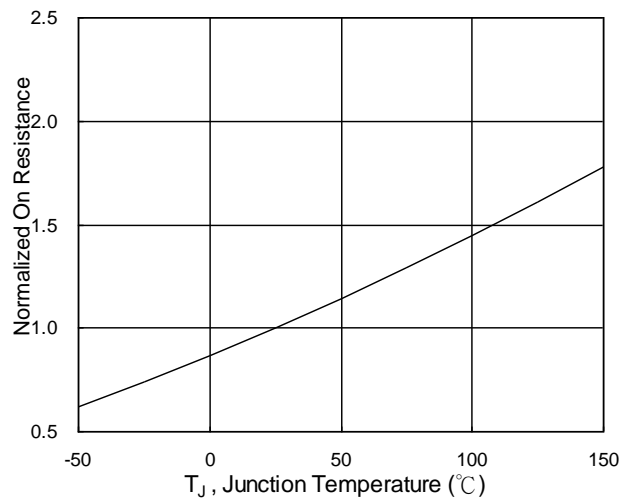
**Fig.3 Source Drain Forward Characteristics**



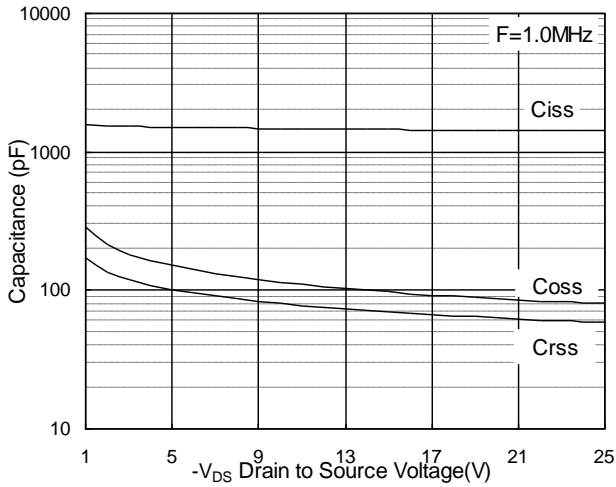
**Fig.4 Gate-Charge Characteristics**



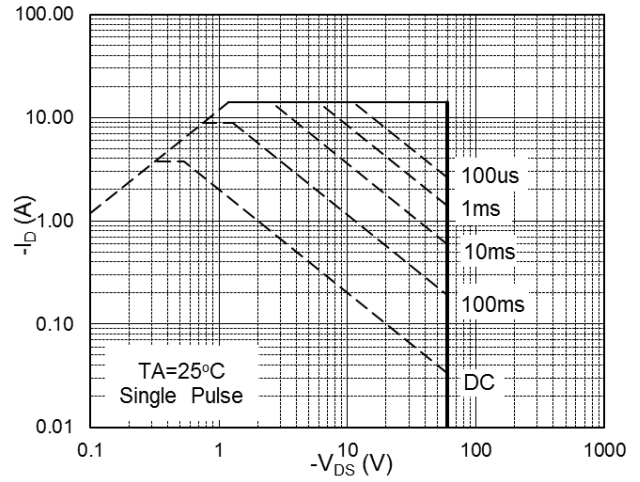
**Fig.5 Normalized  $V_{GS(th)}$  vs  $T_J$**



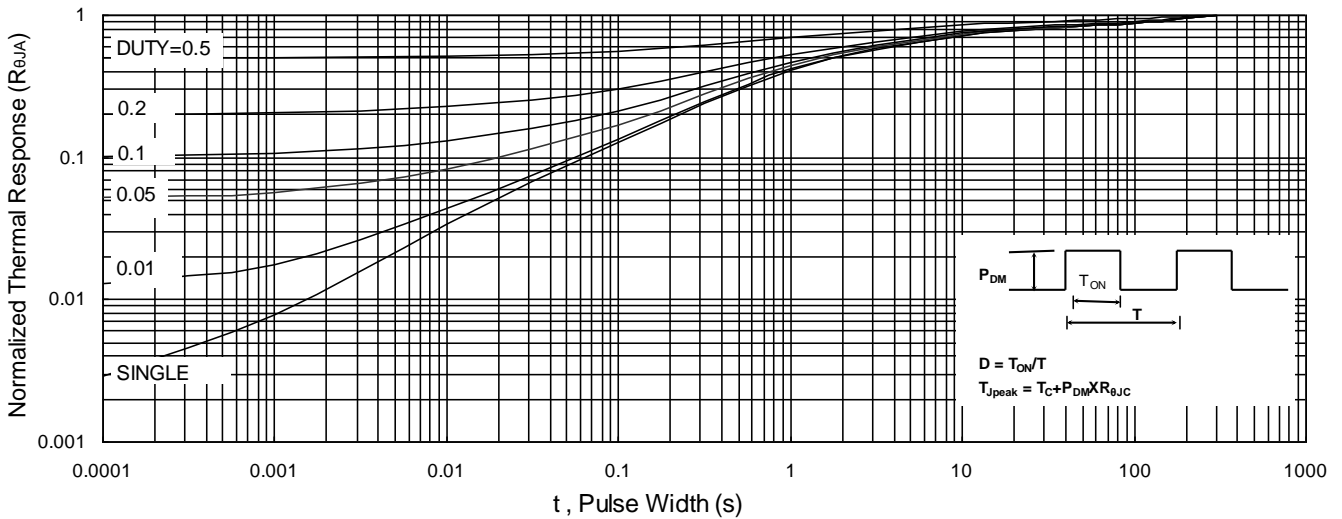
**Fig.6 Normalized  $R_{DS(on)}$  vs  $T_J$**



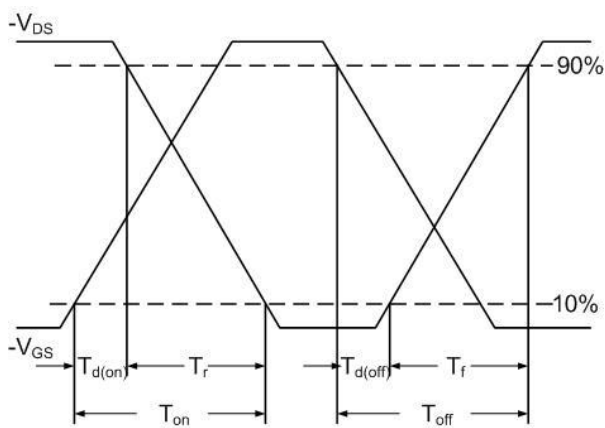
**Fig.7 Capacitance**



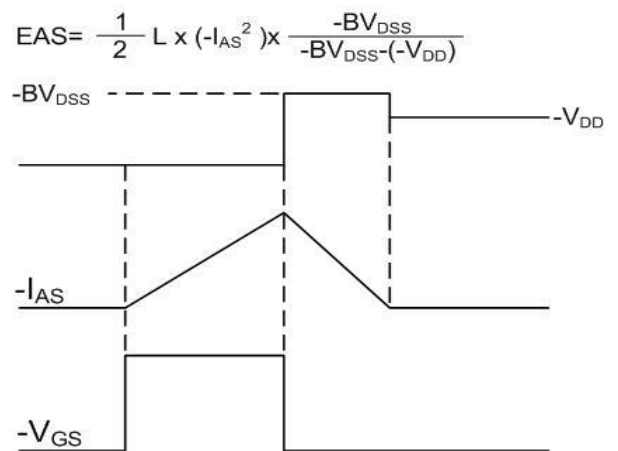
**Fig.8 Safe Operating Area**



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**Fig.10 Switching Time Waveform**



**Fig.11 Unclamped Inductive Waveform**